

85V N-Channel SGT Power MOSFET

Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
85V	2.5mΩ@10V	230A

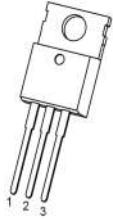
Features

- Fast switching
- 100% EAS Guaranteed
- Green device available

Applications

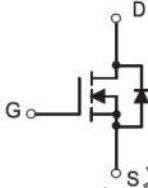
- Motor Drives
- UPS
- DC-DC Converter
- SR
- BMS

TO-220C




PIN1:GATE
PIN2:DRAIN
PIN3:SOURCE

Schematic diagram



Marking



G020N09 : Device Code
YY : Year Code
WW : Week Code

Absolute Maximum rating ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit	
Drain - Source Voltage	V_{DS}	100	V	
Gate - Source Voltage	V_{GS}	±20	V	
Continuous Drain Current	I_D	$T_C = 25^\circ\text{C}$	230	A
		$T_C = 100^\circ\text{C}$	145	
Pulsed drain current	I_{DM}	920	A	
Avalanche energy ¹	E_{AS}	1300	mJ	
Power Dissipation	P_D	227	W	
Thermal Resistance from Junction to Case	$R_{\theta JC}$	0.55	°C/W	
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55~ +150	°C	
Soldering temperature, wave soldering only allowed	T_{sold}	260	°C	

Electrical Characteristics (T_A = 25°C unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Type	Max	Unit
Static Characteristics						
Drain - Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250μA	85			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 85V, V _{GS} = 0V, T _J = 25°C			1	μA
		V _{DS} = 85V, V _{GS} = 0V, T _J = 125°C			100	
Gate - Body Leakage Current	I _{GSS}	V _{GS} = ±20V, V _{DS} = 0V			±100	nA
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250μA	2	3	4	V
Drain-source On-resistance	R _{DS(on)}	V _{GS} = 10V, I _D = 20A, T _J = 25°C		2.5	3.0	mΩ
Forward transconductance	g _{FS}	V _{DS} = 5V, I _D = 20A		55		S
Dynamic Characteristics						
Input Capacitance	C _{iss}	V _{DS} = 40V, V _{GS} = 0V, f= 1MHz		7200		pF
Output Capacitance	C _{oss}			1400		
Reverse Transfer Capacitance	C _{rss}			45		
Gate resistance	R _g	V _{DS} = 0V, V _{GS} = 0V, f= 1MHz		1.6		Ω
Switching Characteristics						
Total Gate Charge	Q _g	V _{DS} = 40V, I _D = 20A, V _{GS} = 10 V		100		nC
Gate-source Charge	Q _{gs}			32		
Gate-drain Charge	Q _{gd}			22		
Gate plateau voltage	V _{plateau}			4.9		V
Turn-on Delay Time	t _{d(on)}	V _{DD} = 40V, V _{GS} = 10V, I _D = 20A, R _g = 3Ω		20		ns
Turn-on Rise Time	t _r			35		
Turn-off Delay Time	t _{d(off)}			55		
Turn-off Fall Time	t _f			30		
Source - Drain Diode Characteristics						
Diode Forward Voltage	V _{SD}	V _{GS} = 0V, I _S = 50A			1.2	V
Reverse Recovery Time	t _{rr}	I _F = 20A, dI/dt= 100A/μs		65		ns
Reverse Recovery Charge	Q _{rr}				150	

Notes :

1. E_{AS} condition: T_J=25°C, V_{DD}= 40V, V_G= 10V, R_g= 25Ω, L= 1mH.

Typical Characteristic

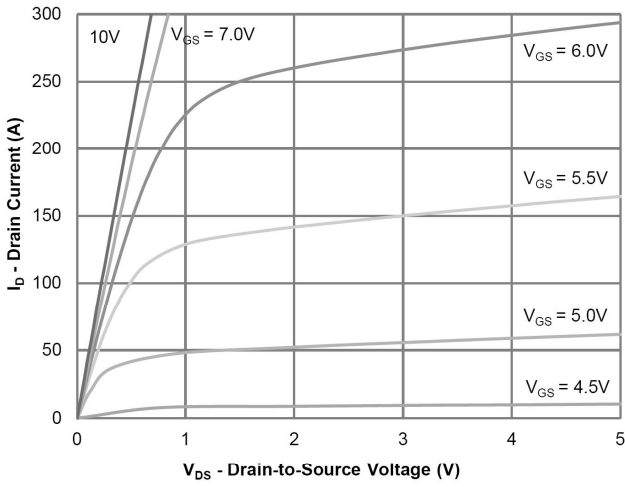


Figure 1: Output Characteristics

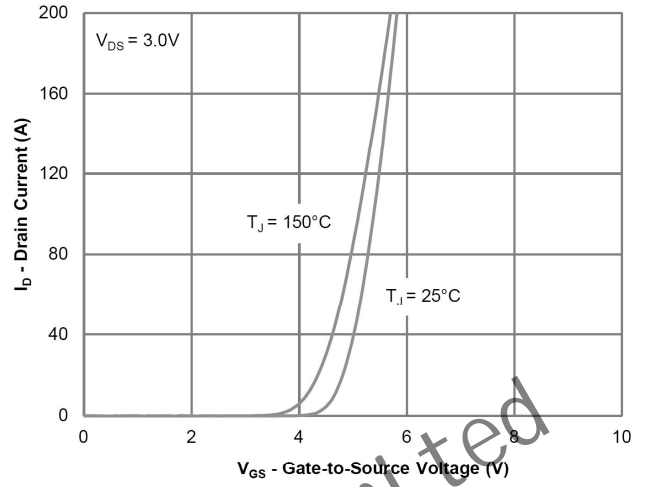


Figure 2: Transfer Characteristics

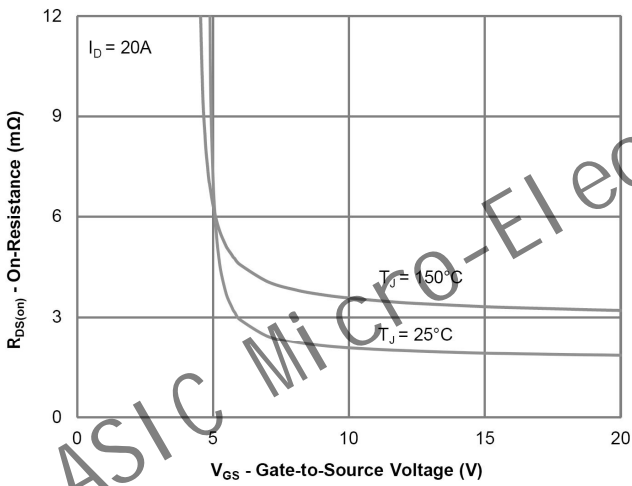


Figure 3: On-Resistance vs. Gate-Source Voltage

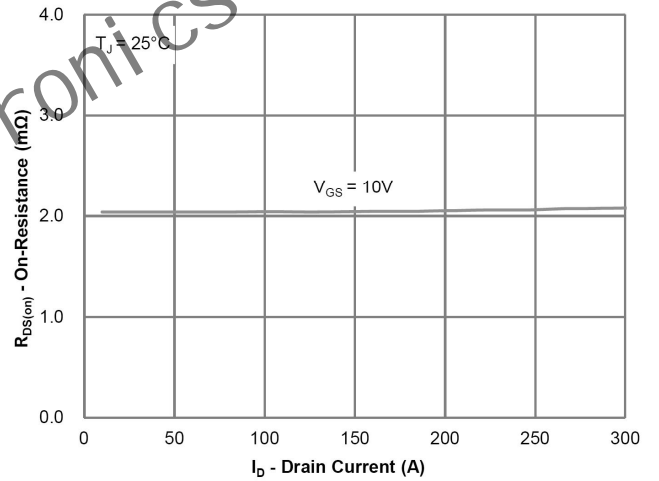


Figure 4: On-Resistance vs. Drain Current and Gate Voltage

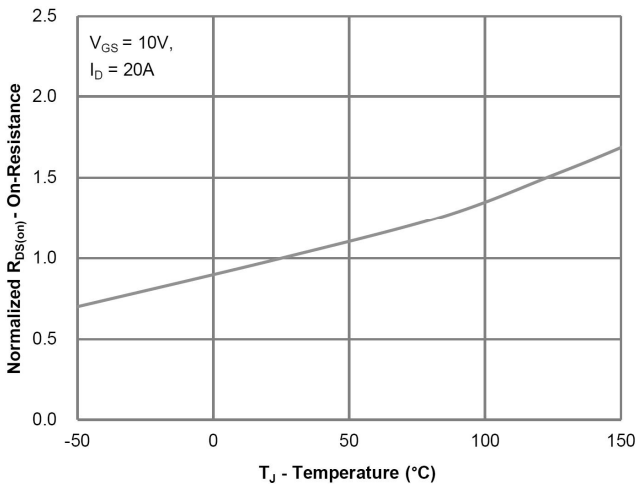


Figure 5: On-Resistance vs. Junction Temperature

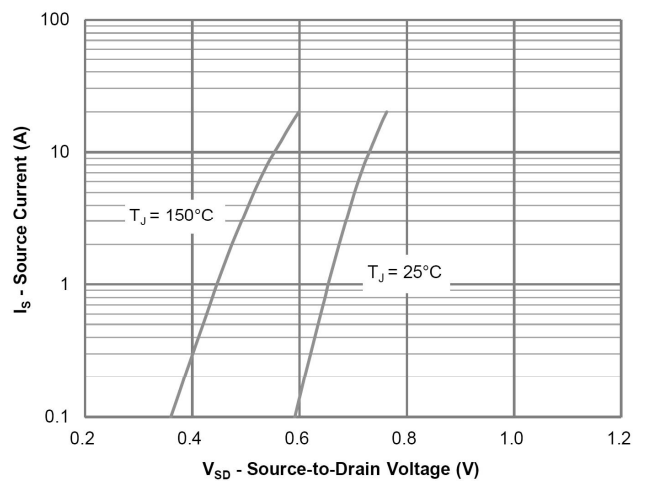


Figure 6: Source-Drain Diode Forward Voltage

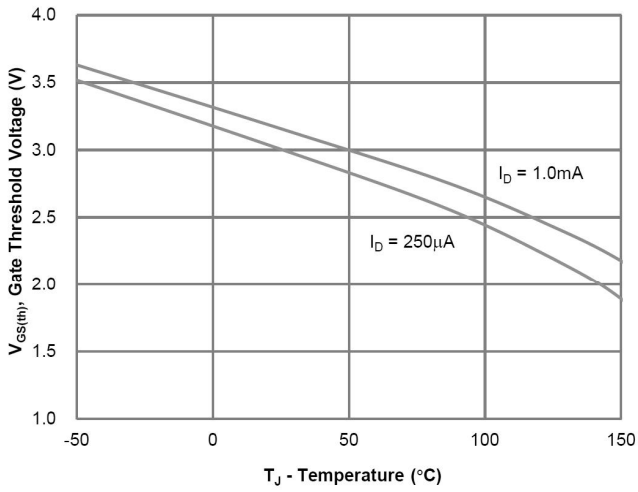


Figure 7: Gate Threshold Variation vs. Junction Temperature

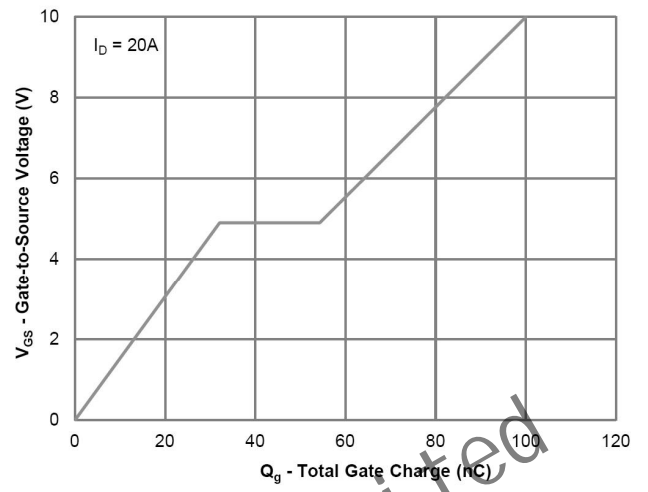


Figure 8: Gate Charge Characteristics

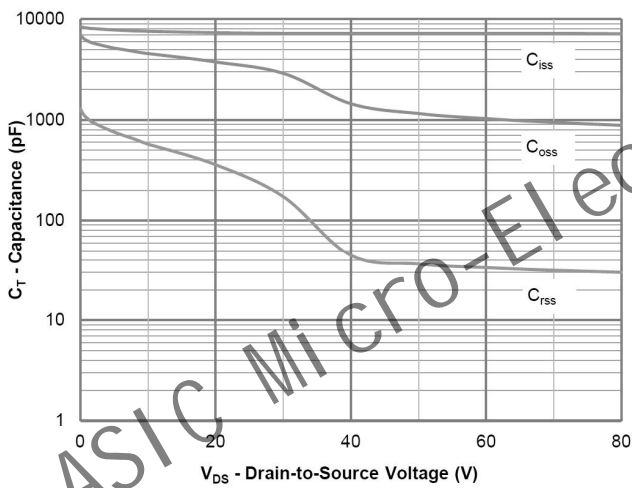


Figure 9: Capacitance Characteristics

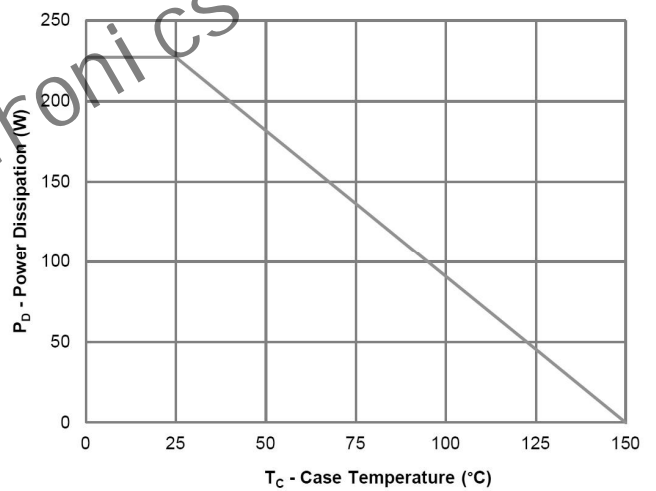


Figure 10: Power Derating

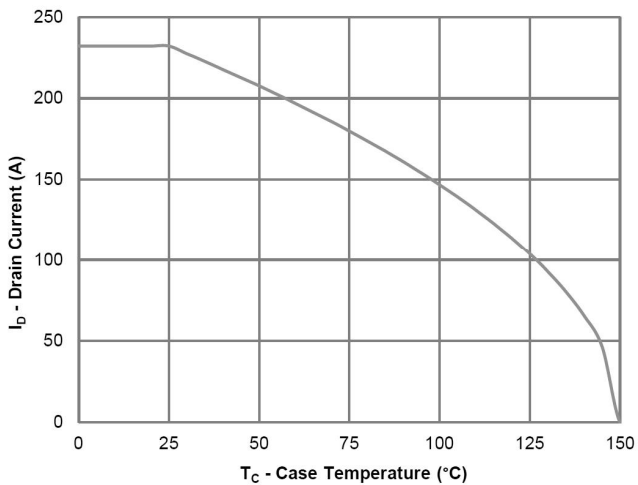


Figure 11: Current Derating

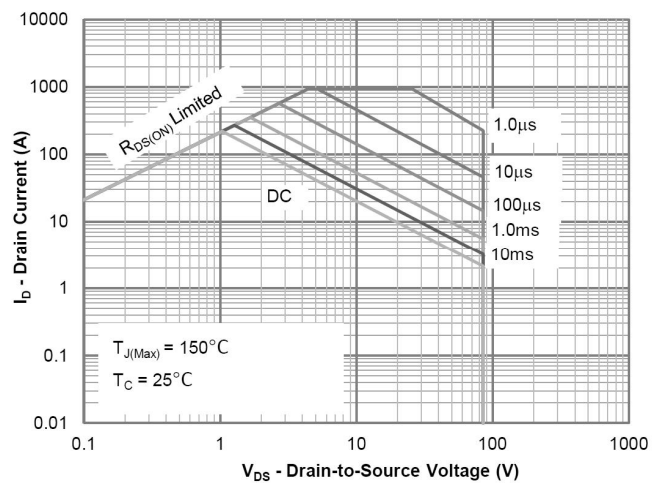
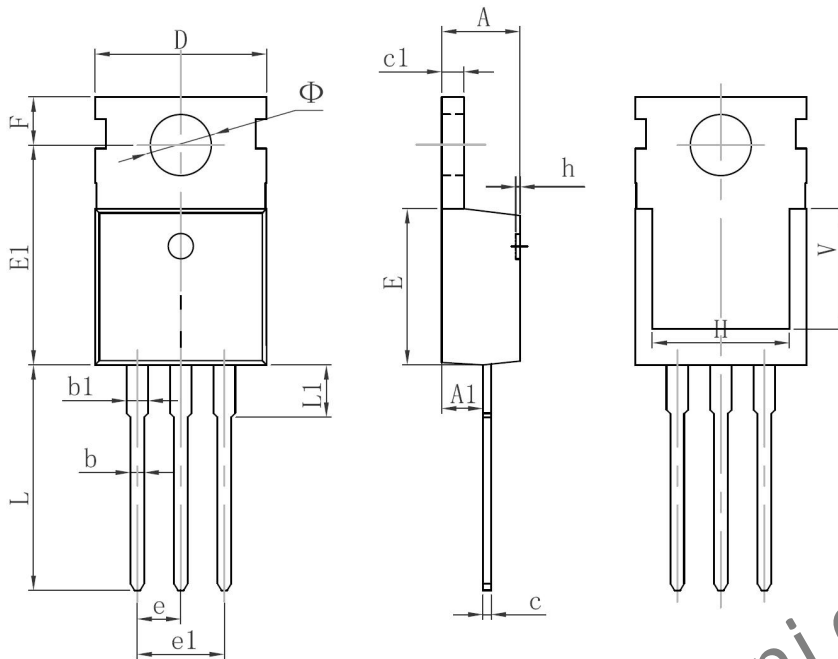


Figure 12: Safe Operating Area

Dimension

TO-220C



Symbol	Millimeters		Inches	
	Min	Max	Min	Max
A	4.400	4.600	0.17	0.18
A1	2.250	2.550	0.08	0.10
b	0.710	0.910	0.02	0.03
b1	1.170	1.370	0.04	0.05
c	0.330	0.650	0.01	0.02
c1	1.200	1.400	0.04	0.05
D	9.910	10.25	0.39	0.40
E	8.950	9.750	0.35	0.38
E1	12.65	12.95	0.49	0.51
e	2.540 TYP.		0.100 TYP.	
e1	4.980	5.180	0.19	0.20
F	2.650	2.950	0.10	0.11
H	7.900	8.100	0.31	0.31
h	0.000	0.300	0.00	0.01
L	12.90	13.40	0.50	0.52
L1	2.850	3.250	0.11	0.12
V	7.500 REF.		0.295 REF.	
Φ	3.400	3.800	0.13	0.15
A	4.400	4.600	0.17	0.18
A1	2.250	2.550	0.08	0.10

ASIC Micro-Electronics Limited